Materials Declaration Form

IPC	**1752**	**Version**	**2**
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	**Subsectionals ***	A-D **** : Required Field***

Supplier Information			
Company Name *	STMicroelectronics	**Response Date ***	22-09-2023
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	**Contact Email ***	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	**Representative Title**	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	**Representative Email ***	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	**Legal Declaration ***	Standard

Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Signature Not
Verified

Digitally signed by
MDF Champion
Date: 2023.09.22
16:04:18 +08:00

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STM32U073CCU6	70MI*489ESXA	A	998Z	22-09-2023
	Amount	UoM	**Unit type**	**ST ECOPACK Grade**
	102.07	mg	Each	ECOPACK® 2
.	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Not Applicable ; if coating is used or other bulk termaination : add in comments	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	7x7x0.55	48	flat	
Comment	Package : A0B9 UFQFPN 7X7X0.55 48L 0.5 MM PITCH 8202210			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**TRUE**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	**Description**

QueryList : REACH-10 Jun 2022	
Query	**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	**true**

CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						**Mfr Item Name**	**70MI*489ESXA**				6000001.0	999999.2
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	2.936	mg	supplier	die	Silicon (Si)	7440-21-3		2.652	mg	903270	25982
				supplier	metallization	Aluminium (Al)	7429-90-5		0.014	mg	4768	137
				supplier	metallization	Copper (Cu)	7440-50-8		0.120	mg	40872	1176
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.039	mg	13283	382
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	341	10
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	341	10
				supplier	Passivation	Silicon Nitride	12033-89-5		0.031	mg	10559	304
				supplier	Passivation	Silicon Oxide	7631-86-9		0.078	mg	26567	764
Glue Epoxy (EN4900GC)	M-011 Other inorganic materials	0.427	mg	Supplier	Organic Compounds	Acrylic resin	Proprietary		0.030	mg	70000	293
				Supplier	Organic Compounds	Polybutadiene derivative	Proprietary		0.009	mg	20000	84
				Supplier	Organic Compounds	Butadiene copolymer	Proprietary		0.006	mg	15000	63
				Supplier	Organic Compounds	Acrylate	Proprietary		0.023	mg	54000	226
				Supplier	Organic Compounds	Epoxy resin	Proprietary		0.013	mg	30000	126
				Supplier	Organic Compounds	Peroxide	Proprietary		0.003	mg	8000	33
				Supplier	Organic Compounds	Additive	Proprietary		0.008	mg	18000	75
				Supplier	Metals	Silver (Ag)	7440-22-4		0.335	mg	785000	3285
Encapsulation (EME-G770)	M-011 Other inorganic materials	35.848	mg	Supplier	Organic Compounds	Epoxy Resin A	Proprietary		0.753	mg	21000	7375
				Supplier	Organic Compounds	Epoxy Resin B	Proprietary		0.753	mg	21000	7375
				Supplier	Organic Compounds	Phenol Resin A	Proprietary		0.753	mg	21000	7375
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		27.977	mg	780450	274096
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		4.134	mg	115320	40501
				Supplier	Organic Compounds	Carbon Black	1333-86-4		0.223	mg	6230	2188
				Supplier	Metallic compounds	Metal Hydroxide	Proprietary		0.502	mg	14000	4917
				Supplier	Organic Compounds	Phenol Resin B	Proprietary		0.753	mg	21000	7375
Bonding wire (Au)	Bonding Wire	0.782	mg	Supplier	Metals	Gold (Au)	7440-57-5		0.782	mg	1000000	7662
Plating (Sn)	M-011 Other inorganic materials	1.078	mg	Supplier	Metals	Tin (Sn)	7440-31-5		1.078	mg	1000000	10565
Leadframe (C7025 + Ag)	Copper & its alloys	61.000	mg	Supplier	Metals	Copper (Cu)	7440-50-8		55.946	mg	917140	548101
				Supplier	Metals	Nickel (Ni)	7440-02-0		1.373	mg	22500	13446
				Supplier	Metals	Silicon (Si)	7440-21-3		0.159	mg	2600	1554
				Supplier	Metals	Magnesium (Mg)	7439-95-4		0.070	mg	1150	687
				Supplier	Metals	Silver (Ag)	7440-22-4		3.453	mg	56610	33831